

	U	1	Document ID	Issue Date	Pages	Title	Current OR
1	<input checked="" type="checkbox"/>	<input type="checkbox"/>	JP 11340229 A	19991210	10	COPPER INTERCONNECTION OF METAL SEED LAYER INSERTION STRUCTURE	
2	<input type="checkbox"/>	<input type="checkbox"/>	EP 954027 A	20020531	10	Interconnect structure for a semiconductor device	

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1			EDELSTEIN, DANIEL CHARLES et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2			EDELSTEIN, D C et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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1	JP 11340229 A	<input type="checkbox"/>
2	US 6181012	<input type="checkbox"/>